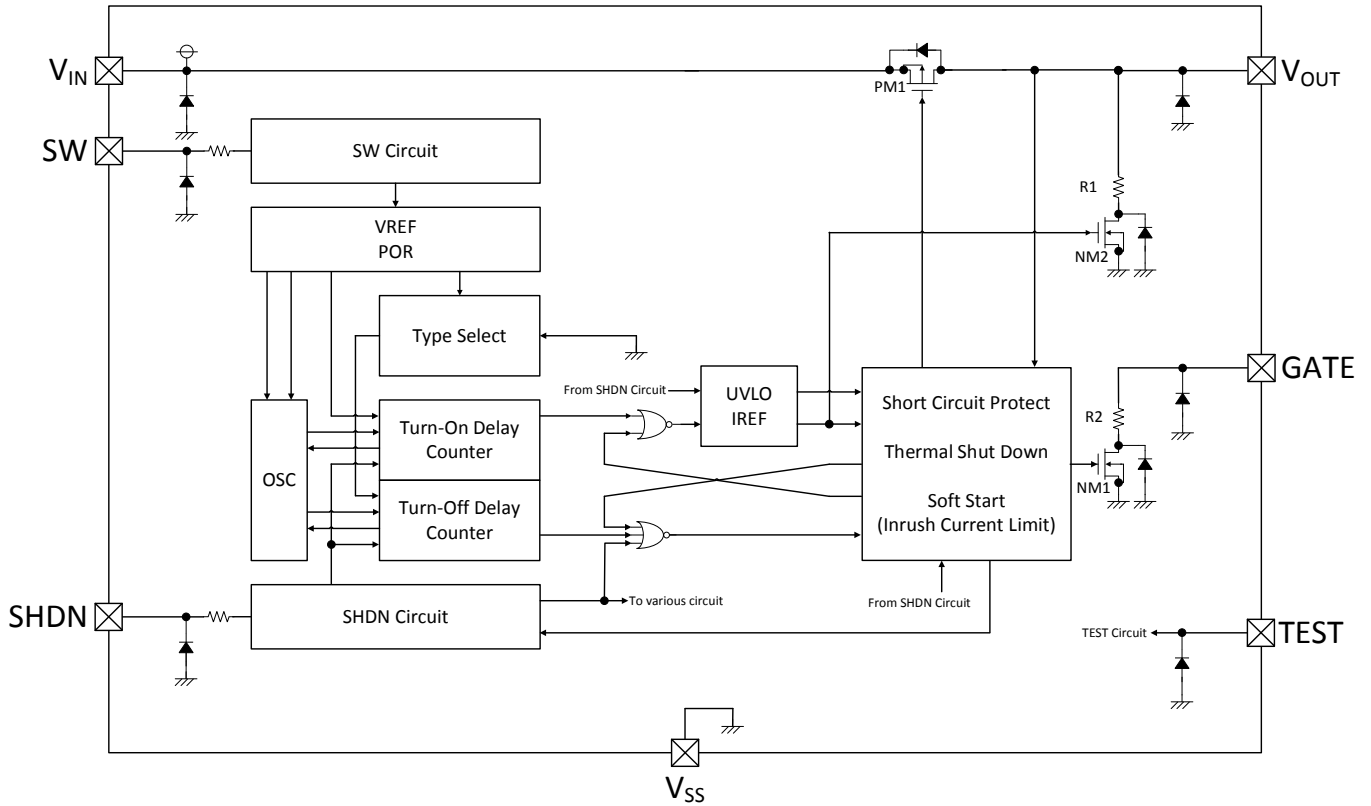
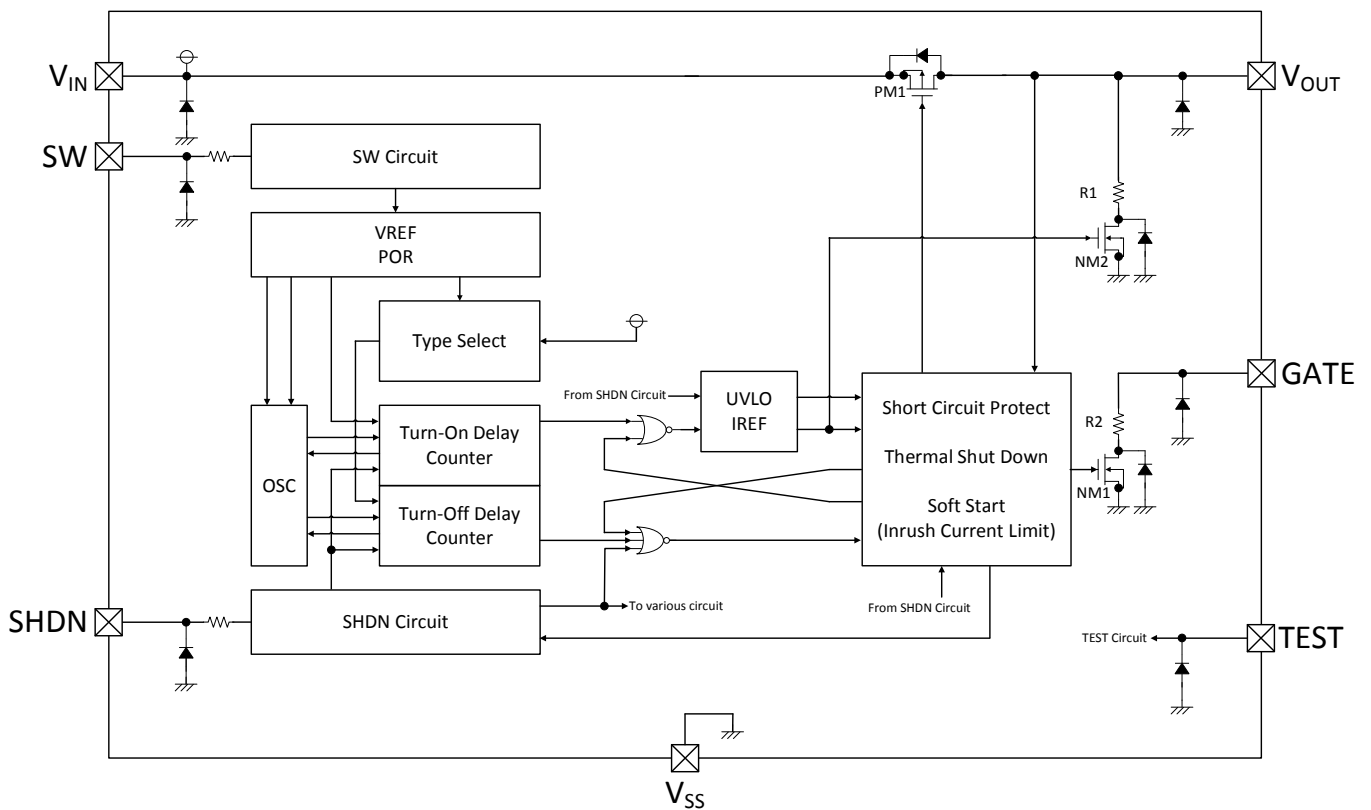


■ BLOCK DIAGRAM

XC6193A



XC6193B



*Diodes inside the circuit are an ESD protection diodes and a parasitic diodes.

■ PRODUCT CLASSIFICATION

● Ordering Information

XC6193①②③④⑤⑥-⑦^(*)

DESIGNATOR	DESCRIPTION	SYMBOL	DESCRIPTION
①	TYPE	A	Turn-on : By the SW pin Shut-down : By the SW pin or the SHDN pin
		B	Turn-on : By the SW pin Shut-down : By the SHDN pin
②	Turn-On delay time	A	0.2s.
		1	1s. option ^{(*)2}
		3	3s. option ^{(*)2}
		5	5s. option ^{(*)2}
③④	Turn-Off delay time	NN	It does not have "Turn-Off function by the SW pin". Applies to XC6193B only.
		03	3s. option ^{(*)2}
		05	5s.
		10	10s.
		15	15s. option ^{(*)2}
⑤⑥-⑦	Package and Taping Type	ER-G	USP-8B06 (5,000pcs/Reel)

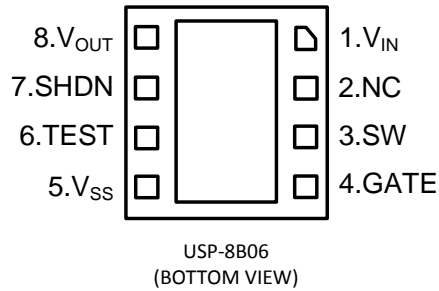
^{(*)1} The "-G" suffix denotes Halogen and Antimony free as well as being fully EU RoHS compliant.

^{(*)2} For option products, please contact your local Torex sales office or representative.

● Selection Guide

Parts No.	Turn-On Delay Time	Turn-Off Delay Time	Package
XC6193AA05ER-G	0.2s	5s	USP-8B06
XC6193AA10ER-G		10s	
XC6193BANNER-G		Not applicable	

PIN CONFIGURATION



*The dissipation pad for the USP-8B06 package should be solder-plated in recommended mount pattern and metal masking so as to enhance mounting strength and heat release.

When taking out a potential of the heat-sink, connect with V_{SS} pin (#5 pin).

PIN ASSIGNMENT

PIN NUMBER	PIN NAME	FUNCTION
USP-8B06		
1	V_{IN}	Power Supply Input
2	NC	No connection pin (The NC pin should be connected the V_{SS} pin or be floated.)
3	SW	Push Button Signal input pin
4	GATE	External Pch MOSFET Control pin
5	V_{SS}	Ground Pin
6	TEST	The TEST pin must be connected the V_{SS} pin.
7	SHDN	Forced Shutdown pin
8	V_{OUT}	Output pin

PIN FUNCTIOS ASSIGNMENT

PIN NAME	SIGNAL	STATUS
SW	L	Active
	H	Keep the current state
	OPEN	Undefined State ^(*)
SHDN	L	Keep the current state
	H	Shut down
	OPEN	Undefined State ^(*)
GATE	Low impedance	V_{OUT} ="H" Level
	High impedance	V_{OUT} ="L" Level

^(*) Please do not leave the SW pin and the SHDN pin open. Each should have a certain voltage

■ ABSOLUTE MAXIMUM RATINGS

Ta=25°C

PARAMETER		SYMBOL	RATINGS	UNITS
VIN Pin Voltage		VIN	-0.3 ~ +6.6	V
VOUT Pin Voltage		VOUT	-0.3 ~ VIN+0.3 or +6.6 ^{(*)1}	V
VOUT Pin Output Current		IOUT	1500	mA
SW Pin Voltage		VSW	-0.3 ~ +6.6	V
SHDN Pin Voltage		VSHDN	-0.3 ~ +6.6	V
GATE Pin Voltage		VGATE	-0.3 ~ +6.6	
TEST Pin Voltage		VTEST	-0.3 ~ VIN+0.3 or +6.6 ^{(*)1}	V
Power Dissipation	USP-8B06	Pd	1240 (JESD51-7 board) ^{(*)2}	mW
Operating Ambient Temperature		Topr	-40 ~ +85	°C
Storage Temperature		Tstg	-55 ~ +125	°C

Each rating voltage is based on the VSS

^{(*)1} Either of lower one, VIN+0.3 or +6.6, is applicable.

^{(*)2} The power dissipation figure shown is PCB mounted and is for reference only.

Please refer to PACKAGING INFORMATION for the mounting condition.

ELECTRICAL CHARACTERISTICS

XC6193 Series

Ta=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT	CIRCUIT
Input Voltage Range	V _{IN}		1.8	-	6.0	V	(1)
Stand-by Current ^(*1)	I _{STB}	V _{IN} =6.0V, V _{SW} =V _{IN}	-0.10	0.001	0.10	μA	(1)
Operation Current ^(*2)	I _{OP}	Turn-Off states, V _{IN} =6.0V, V _{SW} =0V,	-	48	91	μA	(1)
Quiescent Current ^(*3)	I _Q	Turn-On keeps, V _{IN} =6.0V, V _{SW} =V _{IN}	-	0.13	0.42	μA	(1)
UVLO Detect Voltage	V _{UVLO}	Turn-On States, V _{IN} condition	1.1	1.2	1.37	V	(1)
UVLO Detect Delay Time	t _{UVLO}	After UVLO detected	100	-	-	μs	(1)
Turn-On Delay Time ^(*4)	t _{OND}	XC6193xAxx Change the V _{SW} from V _{IN} to 0V.	0.18	0.20	0.22	s	(1)
		XC6193x1xx Change the V _{SW} from V _{IN} to 0V.	0.90	1.00	1.10		
		XC6193x3xx Change the V _{SW} from V _{IN} to 0V.	2.70	3.00	3.30		
		XC6193x5xx Change the V _{SW} from V _{IN} to 0V.	4.50	5.00	5.50		
Turn-Off Delay Time ^{(*5)(*6)}	t _{OFFD}	XC6193Ax03 Change the V _{SW} from V _{IN} to 0V.	2.70	3.00	3.30	s	(1)
		XC6193Ax05 Change the V _{SW} from V _{IN} to 0V.	4.50	5.00	5.50		
		XC6193Ax10 Change the V _{SW} from V _{IN} to 0V.	9.0	10.0	11.0		
		XC6193Ax15 Change the V _{SW} from V _{IN} to 0V.	13.5	15.0	16.5		
Thermal shutdown Detect Temperature	T _{TSD}	After detected the voltage drop due to the ON resistance of the driver transistor.	-	125	-	°C	(1)
Thermal shutdown Release Temperature	T _{TSDR}		-	105	-		
Short Circuit Detect Voltage	V _{SHORT}	V _{OUT} condition	V _{IN} -0.85	V _{IN} -0.55	V _{IN} -0.25	V	(1)
Short Circuit Detect Delay Time	t _{SHORT}	After short detected, V _{SW} =V _{IN}	80	-	-	μs	(1)

Unless otherwise stated, V_{SS} common, V_{IN}=6.0V, V_{SW}=6.0V, V_{SHDN}=0V, V_{PG}=Open, I_{OUT}=0mA, C_{IN}=0.1μF, C_L=0.1μF

(*1) Self-supply current when V_{OUT} is in the Turn-off state and V_{IN} level is input into the V_{SW} pin.

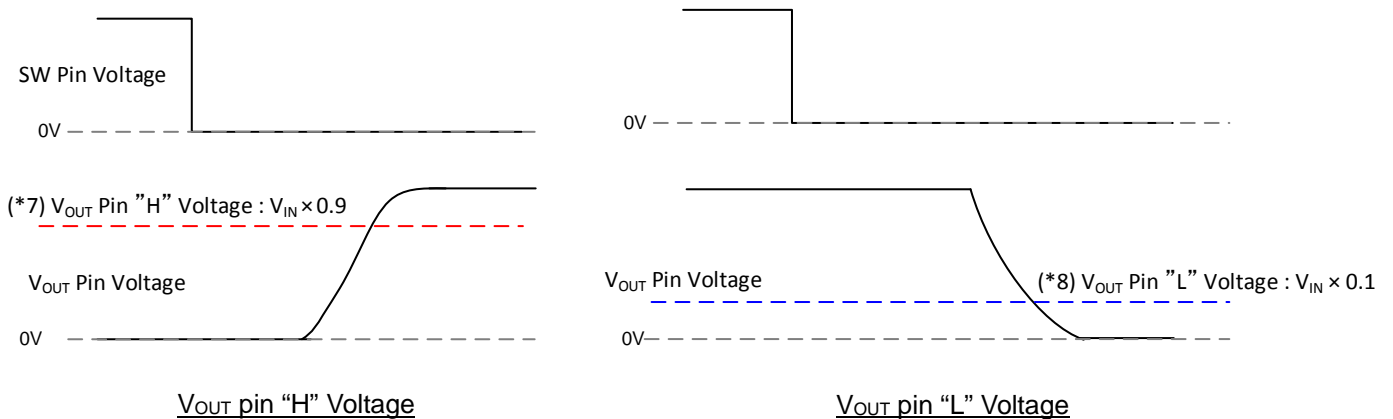
(*2) Self-supply current when V_{OUT} is in the Turn-off state and "L" level is input into the V_{SW} pin.

(*3) Self-supply current when V_{OUT} is in the Turn-on state and V_{IN} level is input into the V_{SW} pin.

(*4) Time from SW pin "L" level until V_{OUT} pin "H" level^(*7) pin in the Turn-off state.

(*5) Time from SW pin "L" level until V_{OUT} pin "L" level^(*8) pin in the Turn-on state.

(*6) Type B does not have this function.



■ ELECTRICAL CHARACTERISTICS (Continued)

XC6193 Series

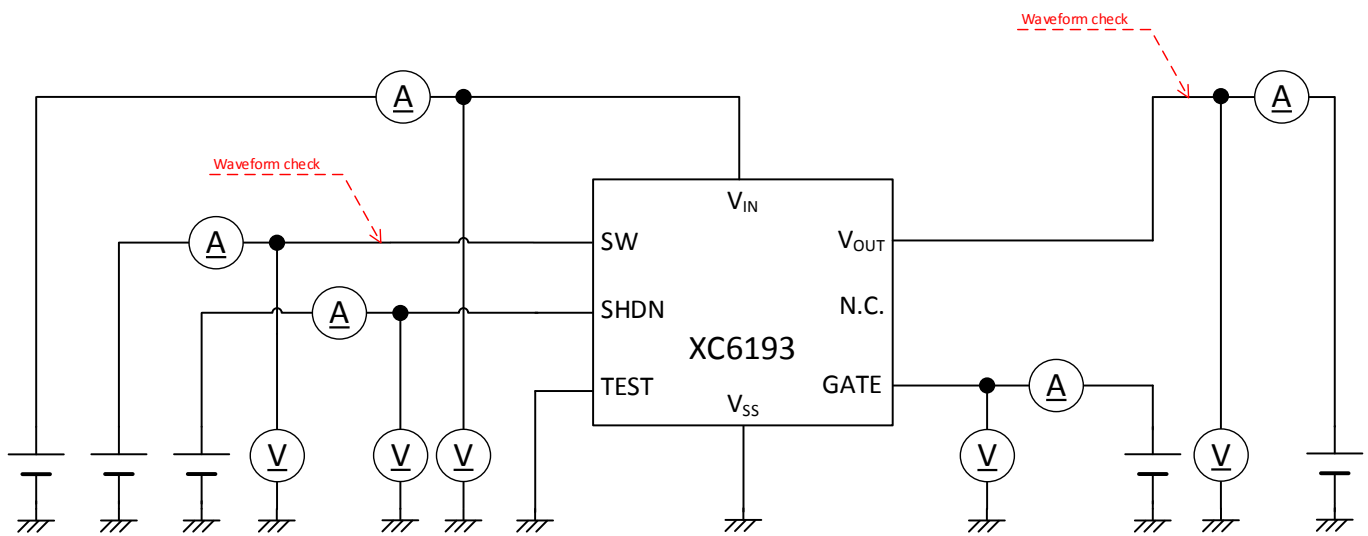
Ta=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT	CIRCUIT
Main Driver On Resistor	R _{ON}	Turn-On states, V _{IN} =1.8V	0.145	0.19	0.46	Ω	(1)
		Turn-On states, V _{IN} =2.0V	0.135	0.18	0.40		
		Turn-On states, V _{IN} =3.0V	0.110	0.14	0.26		
		Turn-On states, V _{IN} =6.0V	0.085	0.11	0.20		
SW pin "H" Voltage	V _{SWH}		1.1	-	6.0	V	(1)
SW pin "L" Voltage	V _{SWL}		0	-	0.4	V	(1)
SW pin "H" Current	I _{SWH}	V _{SW} =6.0V	-0.10	0.01	0.10	μA	(1)
SW pin "L" Current	I _{SWL}	V _{SW} =0V	-0.10	0.01	0.10	μA	(1)
SHDN pin "H" Voltage	V _{SHDNH}		1.1	-	6.0	V	(1)
SHDN pin "L" Voltage	V _{SHDNL}		0	-	0.4	V	(1)
SHDN pin "H" Current	I _{SHDNH}	V _{SHDN} =6.0V	-0.10	0.01	0.10	μA	(1)
SHDN pin "L" Current	I _{SHDNL}	V _{SHDN} =0V	-0.10	0.01	0.10	μA	(1)
GATE pin On Resistor1	R _{GATE1}	Turn-On states, V _{IN} =6.0V, V _{GATE} =0.3V	95	-	-	Ω	(1)
GATE pin On Resistor2	R _{GATE2}	Turn-On states, V _{IN} =1.8V, V _{GATE} =0.3V	-	-	300	Ω	(1)
GATE pin Leak Current	I _{GATEL}	Turn-Off states, V _{IN} =6.0V, V _{GATE} =6.0V	-0.10	0.01	0.10	μA	(1)
CL Discharge Current	I _{DCG}	Turn-Off states, V _{IN} =1.8V, V _{OUT} =0.3V	1	-	-	mA	(1)

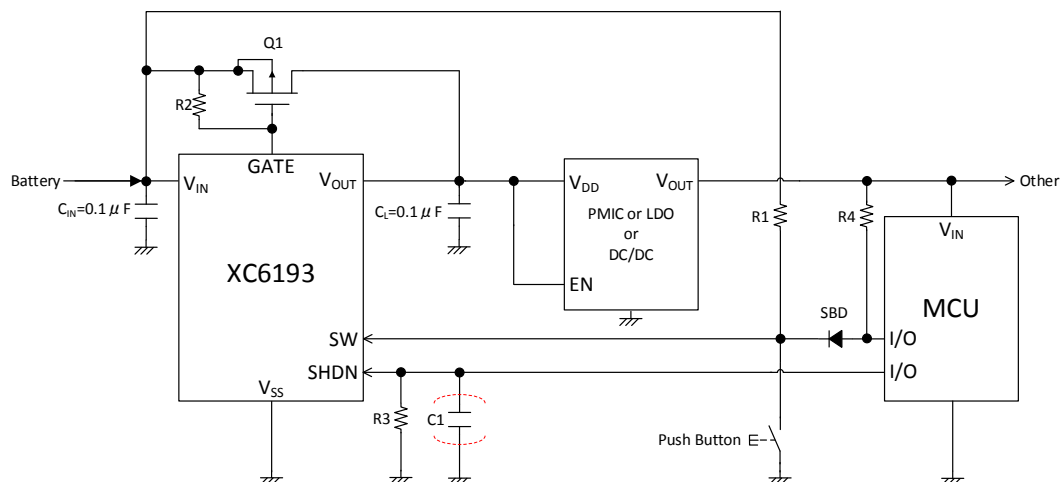
Unless otherwise stated, V_{SS} common, V_{IN}=6.0V, V_{SW}=6.0V, V_{SHDN}=0V, V_{PG}=Open, I_{OUT}=0mA, C_{IN}=0.1μF, C_L=0.1μF

TEST CIRCUITS

Test Circuit (1)



■ TYPICAL APPLICATION CIRCUIT



Example of R2's value selection

(1) Consideration of voltage drop due to the GATE pin leakage current at turn-off states.

- 1) GATE pin Leak Current = 0.1μA (MAX.)
 - 2) Cut-off threshold of the Q1 ($V_{GS_cut\ off}$) = 0.3 V. (Please check the actual Q1's data-sheet.)
- $$R2 \times 0.1\mu A < V_{GS_cut\ off}$$

$$\underline{R2 < 3M\Omega}$$

(2) Consideration of VGS of the Q1 at turn-on states.

- 1) GATE pin On Resistor2 (R_{GATE2}) = 300Ω (MAX.)
 - 2) Turn-on threshold of the Q1 (V_{GS}) = -1.5V ($V_G = V_{IN} + V_{GS} = 0.3V$), (Please check the actual Q1's data-sheet.)
 - 3) $V_{IN} = 1.8V$
- $$R2 > (V_{IN} - V_G) / V_G \times R_{GATE2}$$

$$\underline{R2 > 1.5k\Omega}$$

③ Consideration of current flowing between R2 and Vss at turn-on states.

- 1) GATE pin On Resistor1 (R_{GATE1}) = 95Ω (MIN.)
- 2) The current flowing through to R2 = I_{R2} .

$$\underline{I_{R2} = V_{IN} / (R2 + R_{GATE1})}$$

【Typical Examples】

	VALUE	MANUFACTURER	PRODUCT NUMBER
SBD ^(*)	$V_F = 0.37V$	Panjit	RB751S40
CIN	0.1μF / 10V (Ceramic)		
CL	0.1μF / 10V (Ceramic)		
C1	Set it as necessary. (Example: 0.1μF~ 1μF)		
R1	200kΩ		
R2	1.5kΩ~ 3MΩ-		
R3	5kΩ		
R4	47kΩ		
Q1	$R_{ds} = 112m\Omega @ V_{GS} = -1.8V$	ON Semiconductor	FDZ375P

^(*) Please select freely according to the threshold of the MCU's I/O.

OPERATIONAL EXPLANATION

The XC6193 series type-A fixes V_{OUT} at "H" voltage (same level as the V_{IN} pin voltage) when "L" voltage is input for the required time into the SW pin, and shuts down V_{OUT} (same level as GND) when "L" voltage is subsequently input for the required time into the SW pin, thereby realizing alternating ON/OFF control^(*). Two shutdown methods are available: inputting "H" voltage into the SHDN pin, and inputting "L" voltage the required time into the SW pin.

* Alternating ON/OFF control on this IC is a system that alternates between V_{OUT} "H" voltage and shutdown each time "L" voltage is input for the required time into the SW pin.

The type-B fixes V_{OUT} at "H" voltage when "L" voltage is input for the required time into the SW pin. After V_{OUT} is fixed at "H" voltage, the signal is not accepted if "L" voltage is subsequently input into the SW pin. The shutdown method is inputting "H" voltage into the SHDN pin.

The XC6193 series have be equipped the GATE pin, so it can handle an output current of 1A or more by connecting a Pch MOSFET (Q1) as shown in the typical application circuit.

As protective functions, the XC6193 series are equipped with the inrush current limiting soft-start circuit, the output short protection circuit and the thermal shutdown circuit.

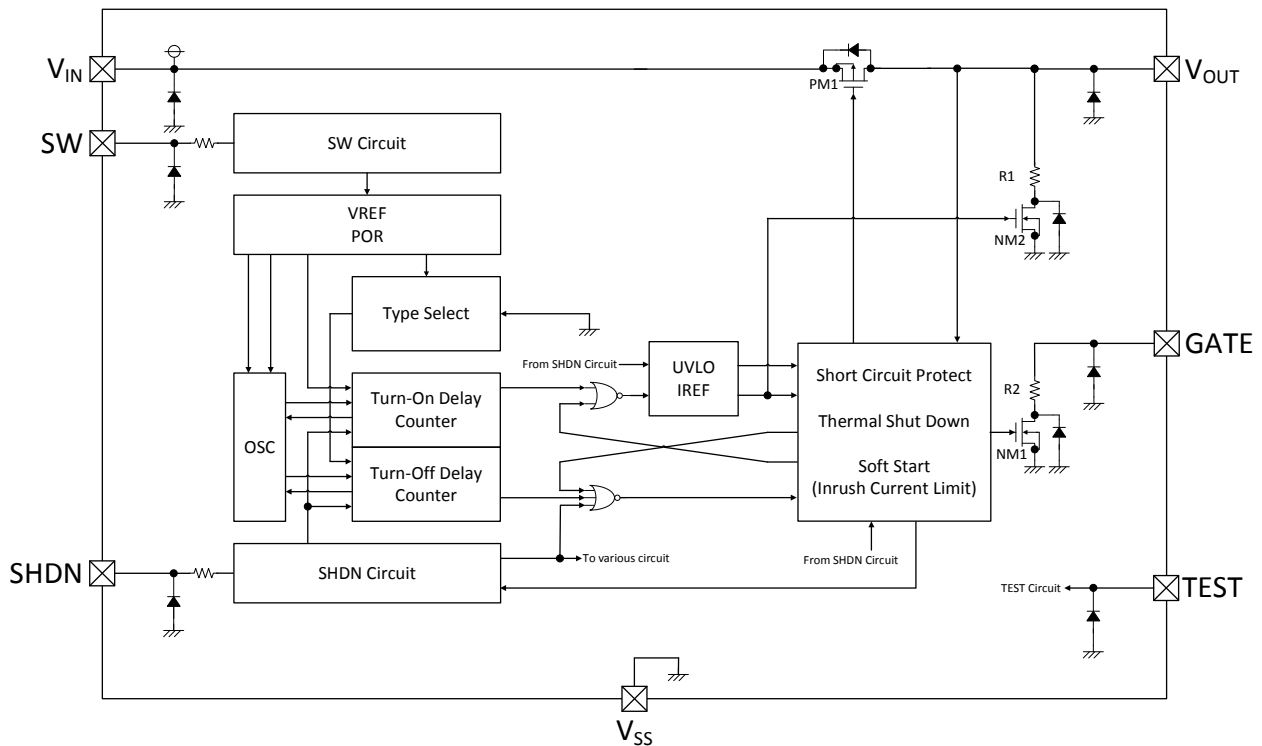


Fig.1 XC6193A Block diagram

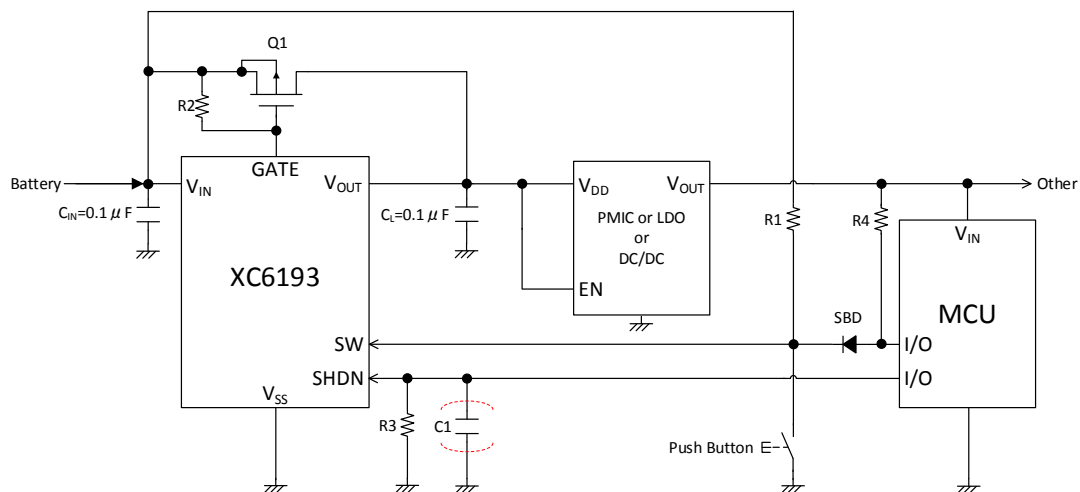


Fig.2 Typical application circuit

■ OPERATIONAL EXPLANATION (Continued)

[Turn-On sequence: Fig.3]

If Voltage “Low” is input over the duration of T_{OND} to the SW pin while V_{OUT} is fixed at Voltage “Low”, V_{OUT} will begin to rise while the output current is being suppressed by the inrush current limit soft-start function, which will gradually turns on the Pch driver transistor PM1 (refer to Fig.1).

Even if the SW pin voltage changes to the Voltage “High” while V_{OUT} is rising, V_{OUT} will ultimately be fixed at Voltage “High”.

When the gate voltage of the PM1 has dropped sufficiently, the Nch transistor: NM1 (refer to Fig.1) connected to the GATE pin will turns on, and the GATE pin will have a low-impedance.

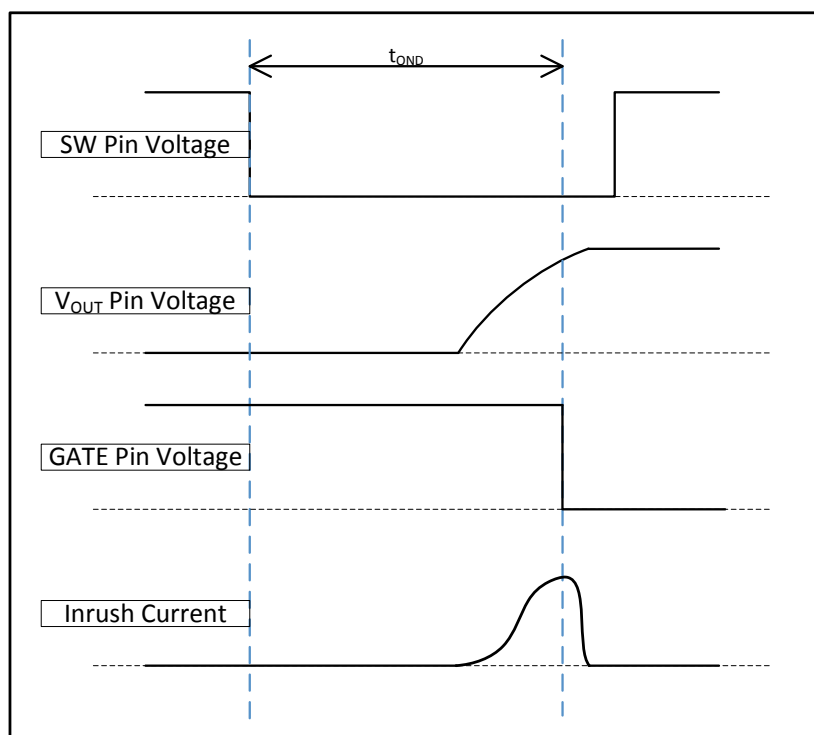


Fig.3 Turn-On sequence

OPERATIONAL EXPLANATION (Continued)

[Shutdown sequence: Fig.4]

In the XC6193 series, when one pulse of "H" voltage (at least 100 μ s as a guideline) is input into the SHDN pin with V_{OUT} fixed at "H" voltage, V_{OUT} changes to the shutdown state and the IC enters the standby state.

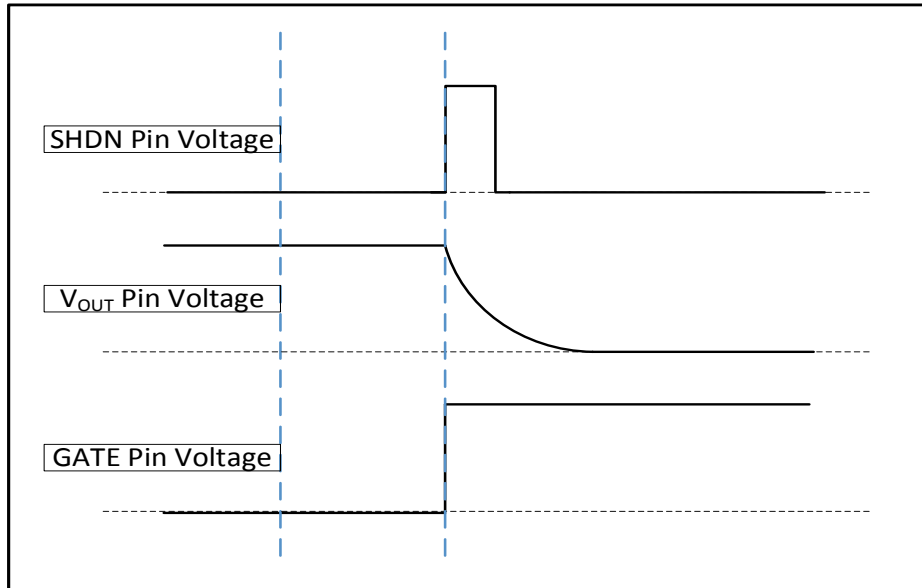


Fig.4 Shutdown sequence

[Turn-Off sequence: Fig.5]

On the A type, when "L" voltage is input into the SW pin for the duration t_{OFFD} with V_{OUT} fixed at "H" voltage, V_{OUT} shuts down. After shutdown, returning the SW pin to "H" voltage reduces the supply current to the standby current while holding the IC's logic. The B type does not have this function.

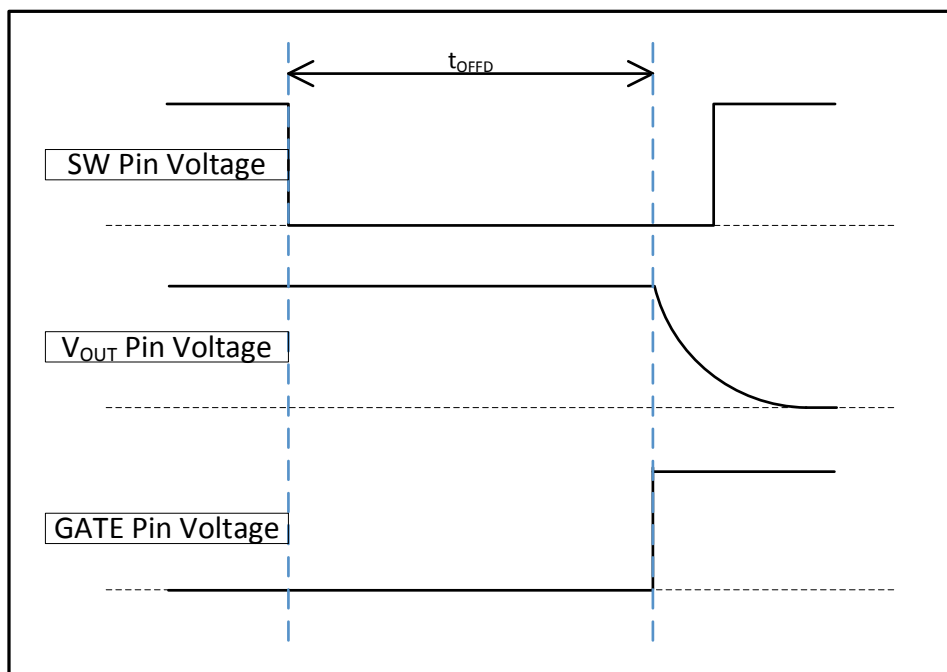


Fig.5 Turn-Off sequence

■ OPERATIONAL EXPLANATION (Continued)

[Operation after Turn-On: Fig.6]

On the A type, when "L" voltage is input into the SW pin for the duration t_{OND} and V_{OUT} is fixed at "H" voltage, and then "L" voltage is input into the SW pin for the duration t_{OFFD} , the Turn-Off sequence cannot be initiated.

To initiate the Turn-Off sequence, "H" voltage must be input into the SW pin, and then "L" voltage must again be input for the duration t_{OFFD} .

The B type does not have a Turn-Off sequence by SW pin.

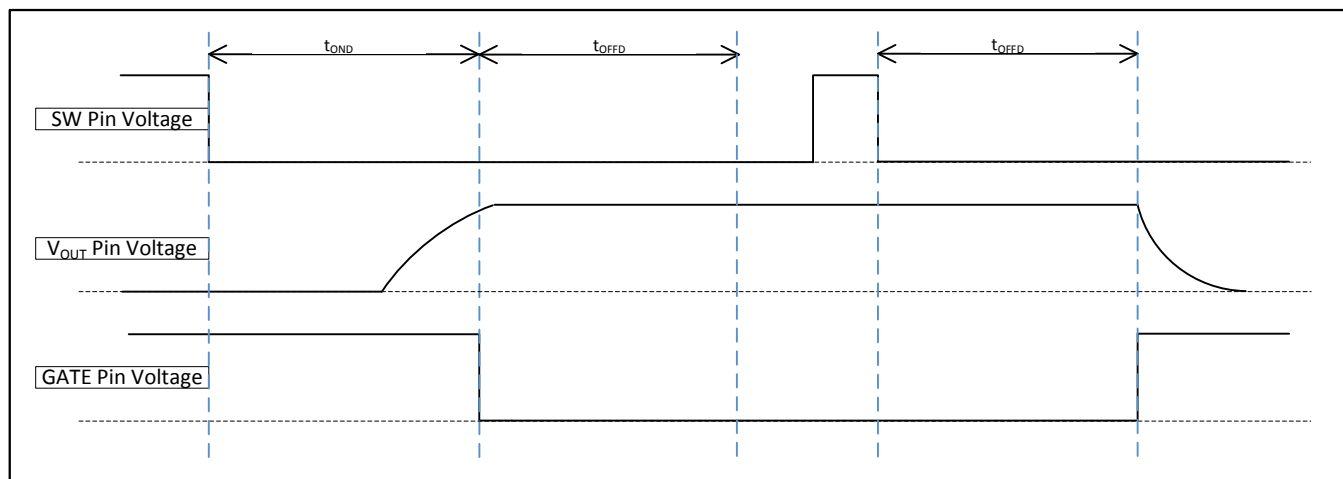


Fig.6 Operation after Turn-On

[Operation after Turn-Off: Fig.7]

On the A type, when "L" voltage is input into the SW pin for the duration t_{OFFD} and V_{OUT} is shut down, and then "L" voltage is input into the SW pin for the duration t_{OND} , the Turn-On sequence cannot be initiated.

To initiate the Turn-On sequence, "H" voltage must be input into the SW pin, and then "L" voltage must again be input for the duration t_{OND} .

The B type does not have a Turn-Off sequence by SW pin.

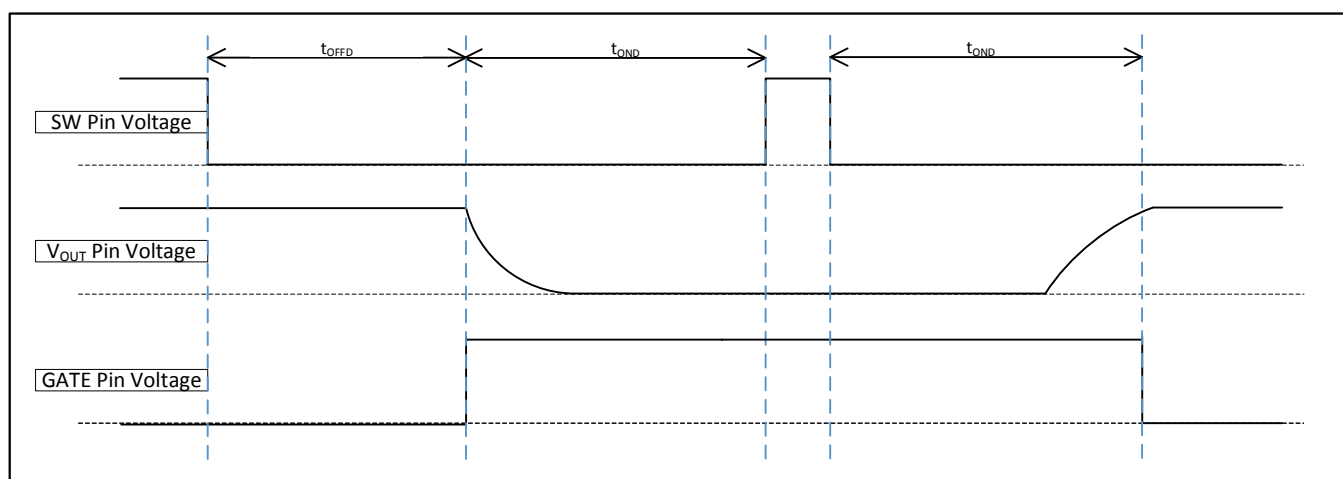


Fig.7 Operation after Turn-Off

OPERATIONAL EXPLANATION (Continued)

[Operation after shutdown: Fig.8]

In the XC6193 series, in order to initiate the Turn-On sequence after "H" voltage is input into the SHDN pin and V_{OUT} is shut down, "H" voltage must be input into the SW pin and then "L" voltage must again be input for the duration t_{OND} .

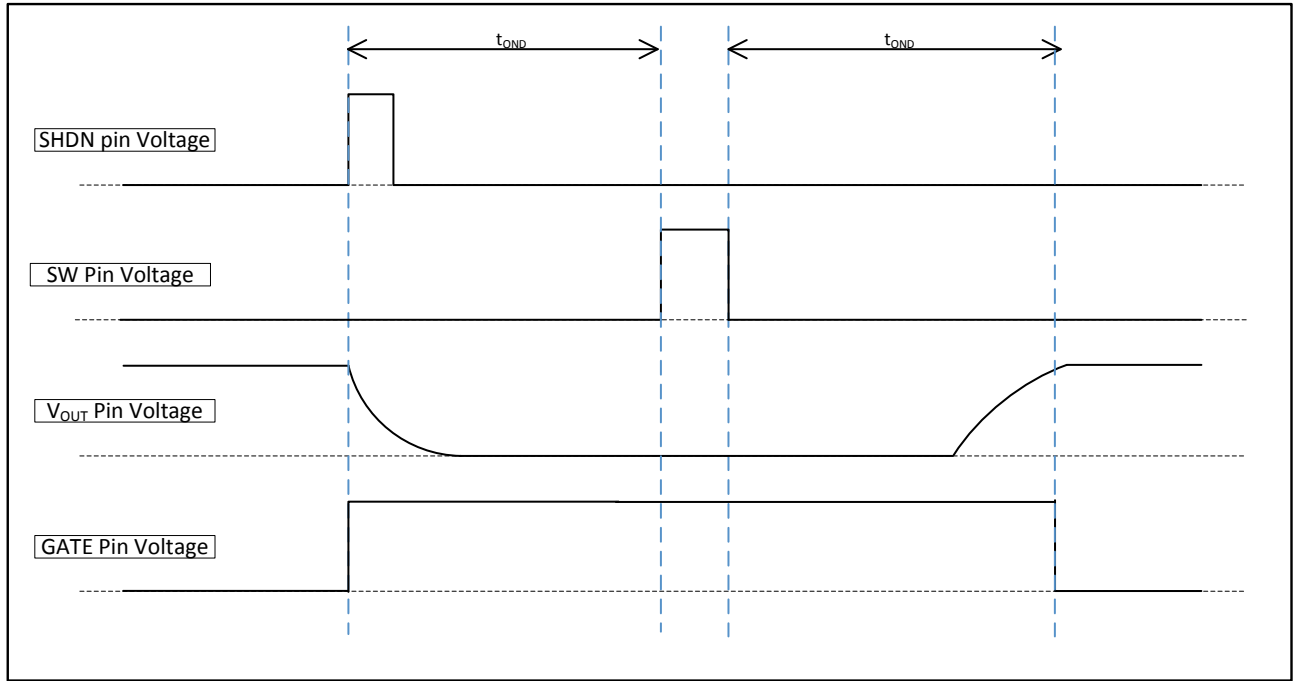


Fig.8 Operation after shutdown

■ OPERATIONAL EXPLANATION (Continued)

[Thermal shutdown function: Fig.9]

The XC6193 series are equipped with thermal shutdown functions.

If a load current causes the V_{OUT} pin voltage to drop by roughly 50mV (TYP.) compared to the V_{IN} pin voltage, the overheat protection circuit will be activated and begin monitoring the IC heat generation.

If the IC temperature is equal to or greater than the Thermal Shutdown Detect Temperature (T_{TSD} : refer to Electrical Characteristics), the function will turn PM1 OFF and stop the supply of load current.

Also, if the discontinuation of the load current supply causes the IC temperature is equal to or less than the Thermal Shutdown Release Temperature (T_{TSDR} : refer to Electrical Characteristics), the IC operation will automatically be restored. The inrush current limit soft start function also operates during automatic restoration.

However, if the V_{OUT} pin voltage is equal to or less than the Short Circuit Detect Voltage (V_{SHORT} : refer to Electrical Characteristics) before the IC temperature is equal to or less than T_{TSDR} , the IC will shut down.

Then, by performing turn-on sequence (refer to Fig.3: Turn-On Sequence), V_{OUT} is turned on again.

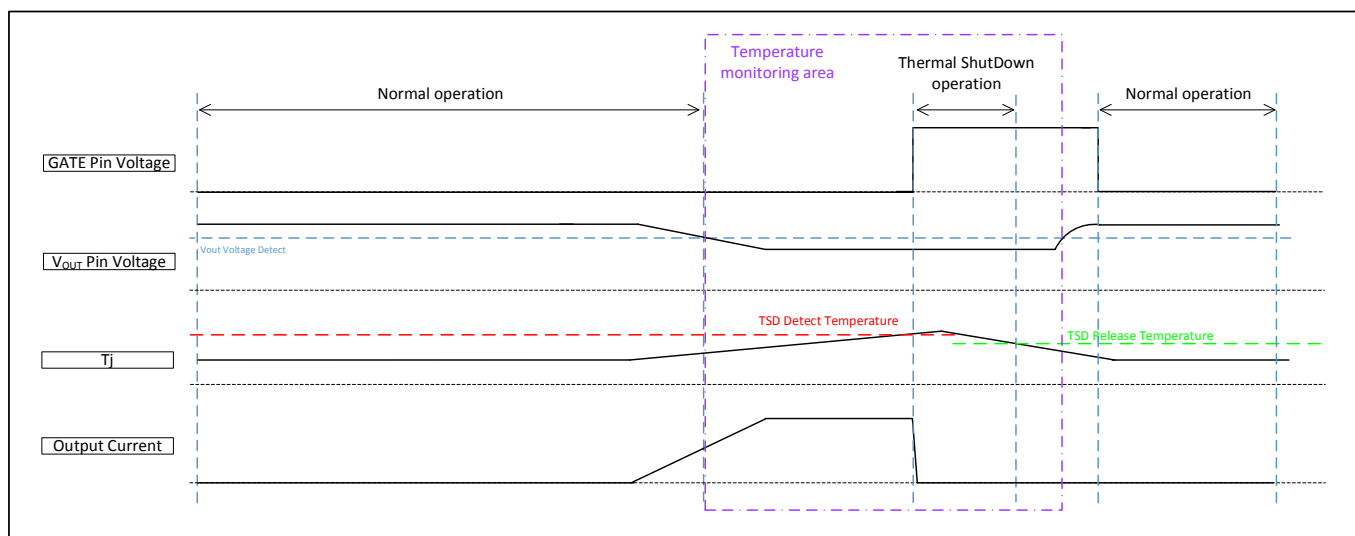


Fig.9 Thermal shutdown function

OPERATIONAL EXPLANATION (Continued)

[Inrush current limit and output short circuit protection: Fig.10]

The XC6193 series are equipped with the inrush current limiting soft-start function and the function of shutting down the output when output short circuit is detected.

After the Turn-On sequence (refer to Fig.3: Turn-On Sequence), if the V_{OUT} pin voltage is equal to or less than the Short Circuit Detect Voltage (V_{SHORT} : refer to Electrical Characteristics) for a duration equal to or longer than the Short Circuit Detect Delay Time (T_{SHORT} : refer to Electrical Characteristics), it will be identified as output short. And the PM1 is latched off-state, causes V_{OUT} to shut down.

The relation between the output current (I_{SHORT}) and V_{SHORT} when output short is given by the equation below.

$$I_{SHORT} = (V_{IN} - V_{SHORT}) / R_{ON} \text{ (A)}$$

- * R_{ON_min} is interlocked with V_{SHORT_max} , and R_{ON_max} is interlocked with R_{ON_min}
- * It is limited to the case of using IC alone.

During the Turn-On sequence, if the V_{OUT} pin voltage is equal to or less than the V_{SHORT} voltage, the output short-circuit protection function will not operate.

Once the V_{OUT} pin voltage is greater than the V_{SHORT} voltage, the output short-circuit protection function will begin to operate.

The equation for the maximum output current is as follows.

$$I_{OUT} \text{ (Min.)} = (V_{IN} - V_{SHORT_max}) / R_{ON_min} \text{ (A)}$$

- * It is limited to the case of using IC alone.

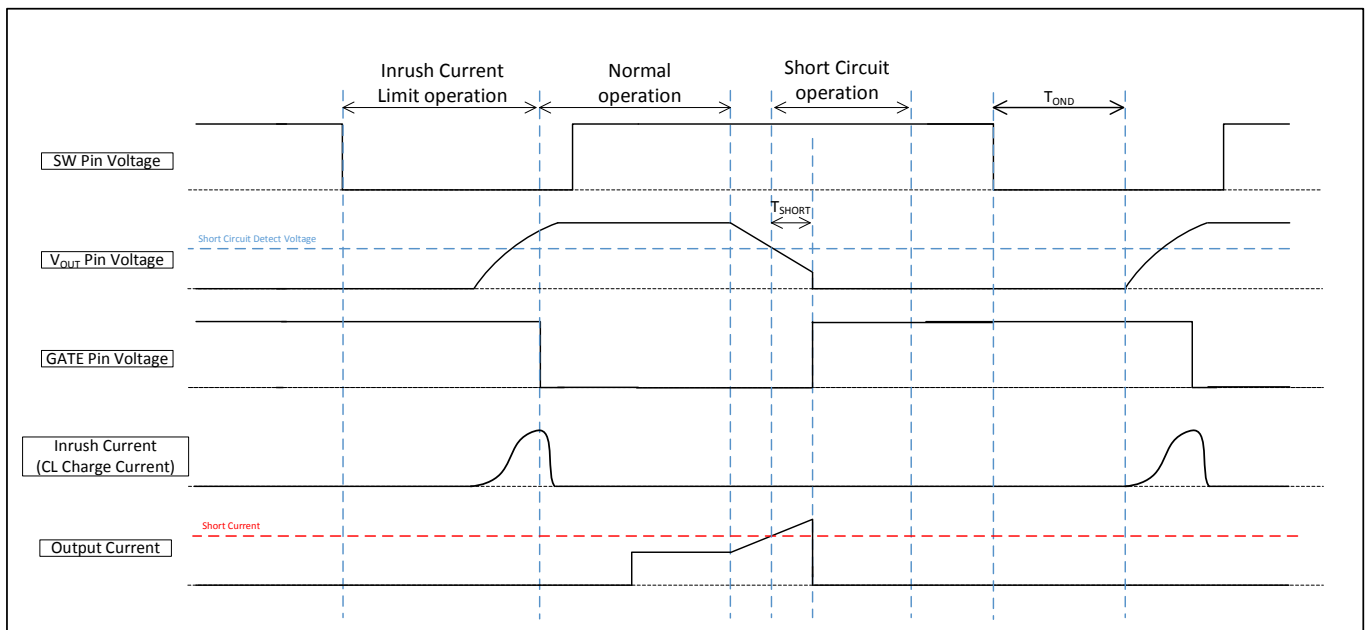


Fig.10 Inrush current limit and short circuit protection

■ OPERATIONAL EXPLANATION (Continued)

[SW pin]

When “L” voltage is input into the SW pin for the duration t_{OND} with the IC in the standby state, the pin fixes V_{OUT} at “H” voltage. On the A type, when V_{OUT} is fixed at “H” voltage, “L” voltage can be input for the duration t_{OFFD} to shut down V_{OUT} .

[SHDN pin]

This pin shuts down V_{OUT} when one pulse of “H” voltage (100 μ s or more as a guideline) is input into the SHDN pin with V_{OUT} fixed at “H” voltage.

[GATE pin]

GATE pin are connected with NM1 and R2(Fig.1).

Since NM1 is the N-ch MOSFET and it is synchronized with the GATE signal of PM1, if PM1 turns ON at the GATE pin, NM1 will turn ON, and if PM1 turns OFF, NM1 will turn OFF.

[VOUT pin]

V_{OUT} pin is connected with PM1, R1 (Fig.1) and CL discharge transistor NM2 (Fig.1).

PM1 is a Pch MOSFET and functions as the main driver.

NM2 is an Nch MOSFET, and is synchronized with the GATE signal of PM1. Therefore, when PM1 turns ON, NM2 turns OFF.

[SW Circuit]

This circuit transmits the signal input into the SW pin to the internal circuitry.

[SHDN Circuit]

This circuit transmits the signal input into the SHDN pin to the internal circuitry.

[VREF & POR]

This circuit supplies the internal circuit with reference voltage as well as a reset signal to the logic circuitry.

[Type Select]

This circuit selects the product type.

[Turn-On Delay Counter]

This circuit count-controls the time until V_{OUT} is fixed at “H” voltage after “L” voltage is input into the SW pin.

During the time until the count is completed, the counter circuit can be returned to the initial state by inputting “H” voltage into the SW pin.

[Turn-Off Delay Counter]

This circuit only operates on the A type.

When V_{OUT} is fixed at “H” voltage, this circuit count-controls the time from input of “L” voltage into the SW pin until V_{OUT} shuts down.

During the time until the count is completed, the counter circuit can be returned to the initial state by inputting “H” voltage into the SW pin.

[UVLO]

It is Under Voltage Lock Out circuit. V_{OUT} will shut down if the input voltage is less than V_{UVLO} .

[IREF]

It is internal circuit reference current source.

[Soft Start (Inrush Current Limit)]

A circuit which slowly switches the PM1 gate voltage from Voltage “High” to Voltage “Low”, and limits the inrush current.

[Short Circuit Protect]

This circuit outputs a signal to shut down if the V_{OUT} pin voltage reaches V_{SHORT} .

Also, this function will stop until V_{OUT} turns ON and reaches V_{SHORT} . Until then, only the Thermal Shutdown circuit will operate as a protection function.

[Thermal Shutdown]

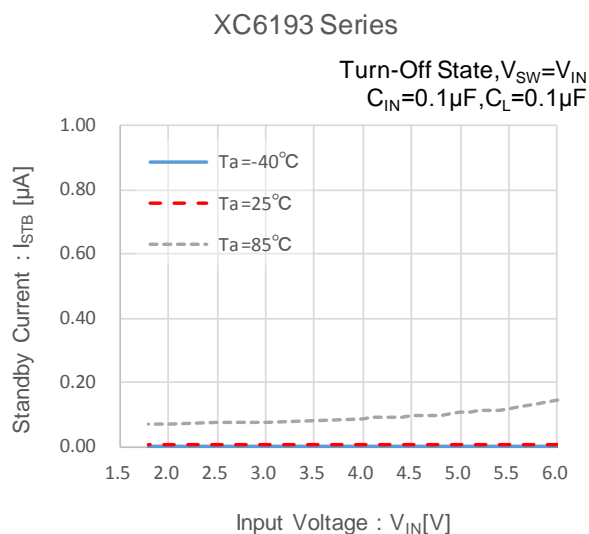
If a load current causes the V_{OUT} pin voltage to drop by roughly 50mV (TYP.) compared to the V_{IN} pin voltage, this function will begin monitoring the IC heat generation. If the IC temperature is equal to or greater than T_{TSDD} , it will turn off the PM1 and stop the supply of load current.

■ NOTES ON USE

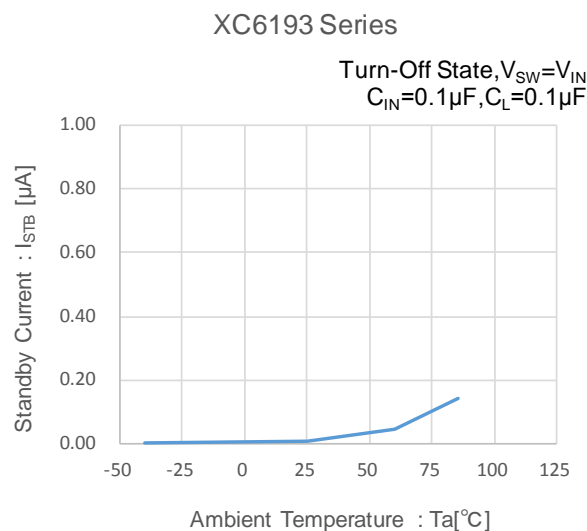
- 1) For temporary, transitional voltage drop or voltage rising phenomenon, the IC is liable to malfunction should the ratings be exceeded.
- 2) Please use this IC within the specified operating ranges.
- 3) In some cases, power supply noise may cause malfunctioning of the internal counter circuit. Sufficiently reinforce the V_{IN} , V_{OUT} , and GND lines, and connect 0.1 μ F or higher capacitors near the IC between V_{IN} and GND (V_{SS}), and between V_{OUT} and GND (V_{SS}).
- 4) When using the capacitor larger than 100 μ F for C_L , it is possible that Inrush Current becomes large. Please sufficiently test actual operation before use.
- 5) When "L" level is input into the SW pin, Operation Current flows. Sufficiently test actual operation before designing peripheral circuits.
- 6) The SW pin and SHDN pin are connected to the gate of a CMOS inverter. If a voltage lower than the V_{IN} pin voltage or a voltage higher than the V_{SS} pin voltage is input into each pin, the flow-through current of the CMOS inverter may appear as supply current.
- 7) If an intermediate voltage between "L" voltage and "H" voltage is input into the SW pin or SHDN pin, starting and stopping of the IC may become unstable. Sufficiently test peripheral components and other parts to ensure that an intermediate voltage between "L" voltage and "H" voltage is not continuously input for an excessive time into the SW pin and the SHDN pin.
- 8) Since electromagnetic wave may cause unexpected malfunction, please reinforce the shielding of the equipment and connect a filter to each terminal as necessary and fully check with actual equipment before using.
- 9) The TEST pin must be connected to GND (V_{SS}).
- 10) When transiently varying the input voltage, please make sure to set the slew rate under 1V/ μ s.
- 11) When using for an application other than a push-button application, please design the timing to include deviations and test sufficiently with the actual device before use.
- 12) Torex places an importance on improving our products and their reliability.
We request that users incorporate fail-safe designs and post-aging protection treatment when using Torex products in their systems.

TYPICAL PERFORMANCE CHARACTERISTICS

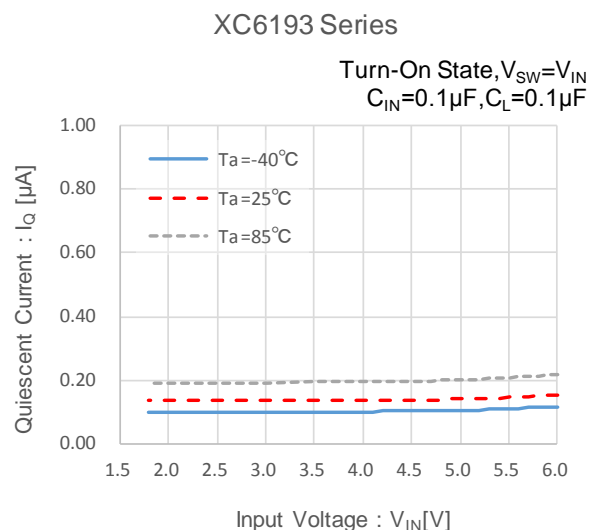
(1) Standby Current vs. Input Voltage



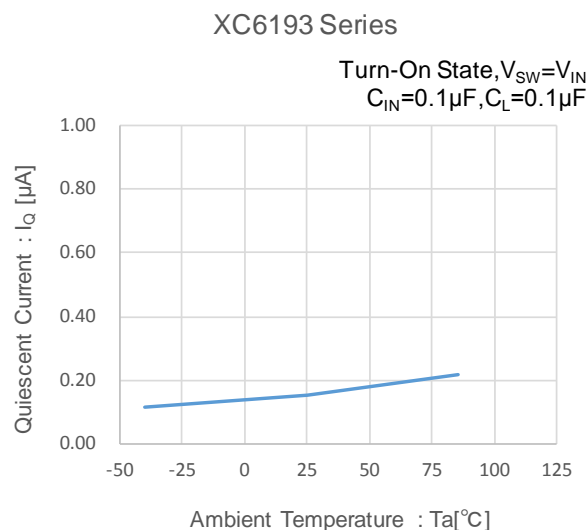
(2) Standby Current vs. Ambient Temperature



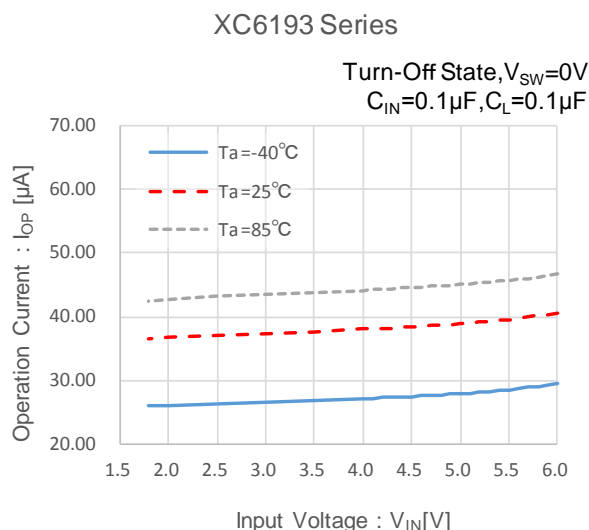
(3) Quiescent Current vs. Input Voltage



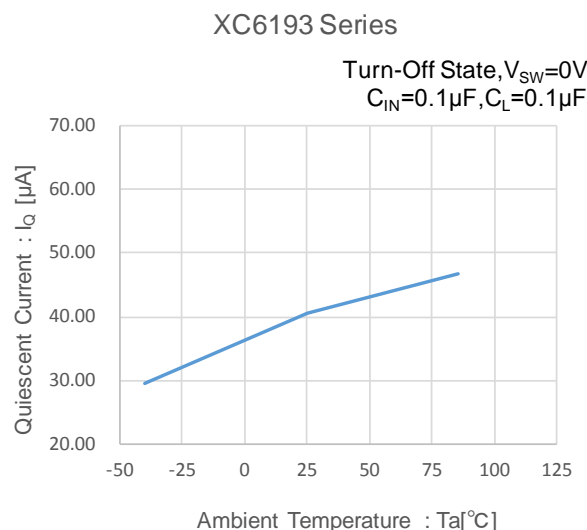
(4) Quiescent Current vs. Ambient Temperature



(5) Operation Current vs. Input Voltage



(6) Operation Current vs. Ambient Temperature

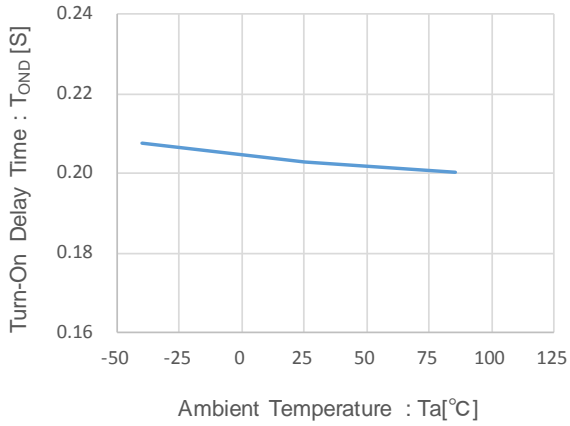


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(7) Turn-On Delay Time vs. Ambient Temperature

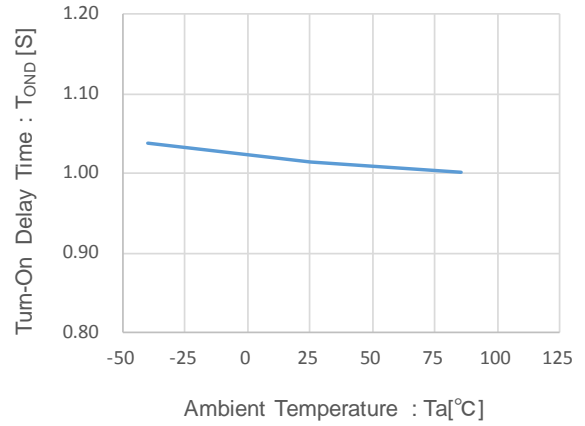
XC6193xAxx

$V_{IN}=3.0V, V_{SW}=V_{IN}>0V$
 $C_{IN}=0.1\mu F, C_L=0.1\mu F$



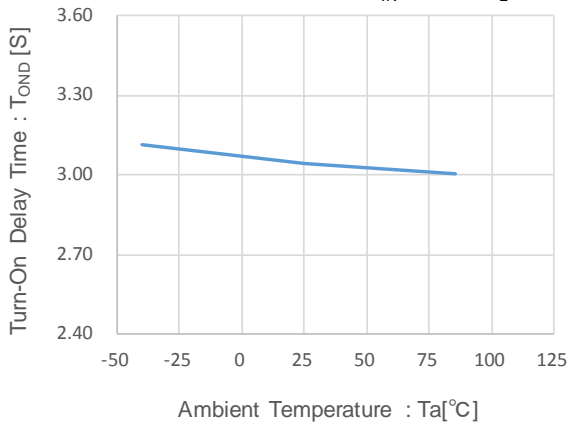
XC6193x1xx

$V_{IN}=3.0V, V_{SW}=V_{IN}>0V$
 $C_{IN}=0.1\mu F, C_L=0.1\mu F$



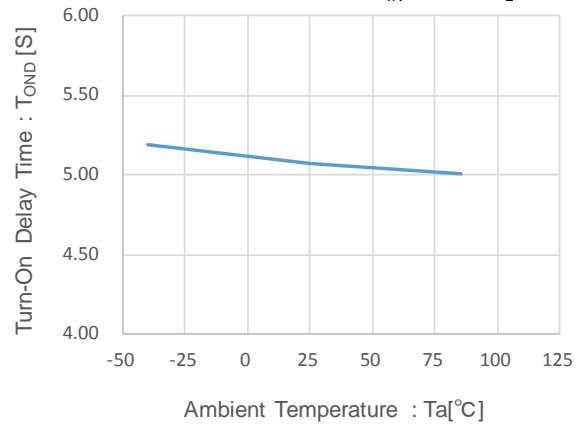
XC6193x3xx

$V_{IN}=3.0V, V_{SW}=V_{IN}>0V$
 $C_{IN}=0.1\mu F, C_L=0.1\mu F$



XC6193x5xx

$V_{IN}=3.0V, V_{SW}=V_{IN}>0V$
 $C_{IN}=0.1\mu F, C_L=0.1\mu F$

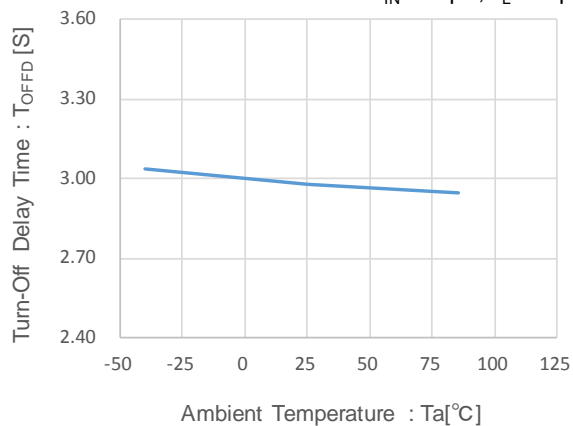


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(8) Turn-Off Delay Time vs. Ambient Temperature

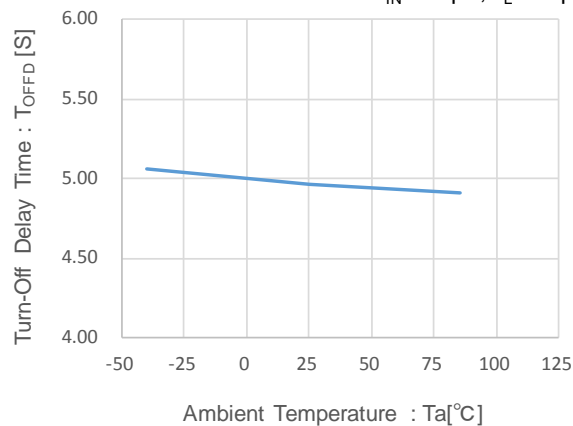
XC6193Ax03

$V_{IN}=3.0V, V_{SW}=V_{IN}>0V$
 $C_{IN}=0.1\mu F, C_L=0.1\mu F$



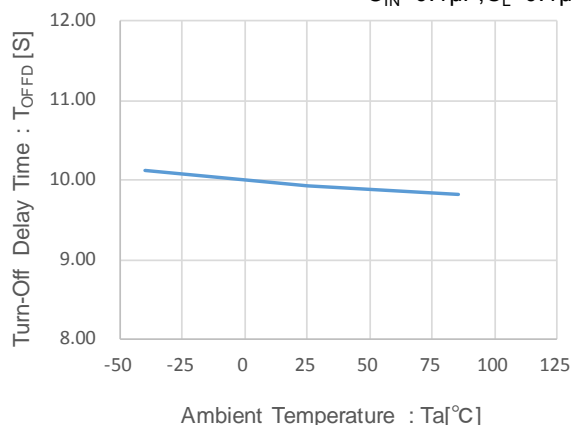
XC6193Ax05

$V_{IN}=3.0V, V_{SW}=V_{IN}>0V$
 $C_{IN}=0.1\mu F, C_L=0.1\mu F$



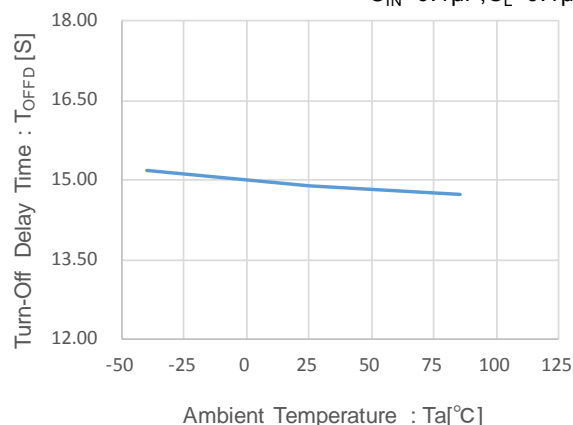
XC6193Ax10

$V_{IN}=3.0V, V_{SW}=V_{IN}>0V$
 $C_{IN}=0.1\mu F, C_L=0.1\mu F$



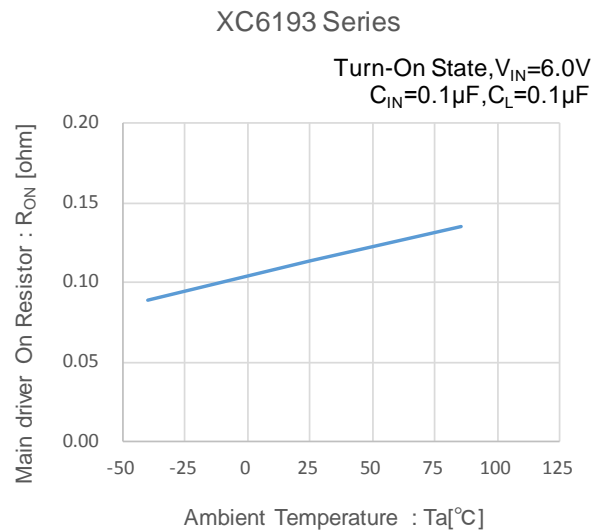
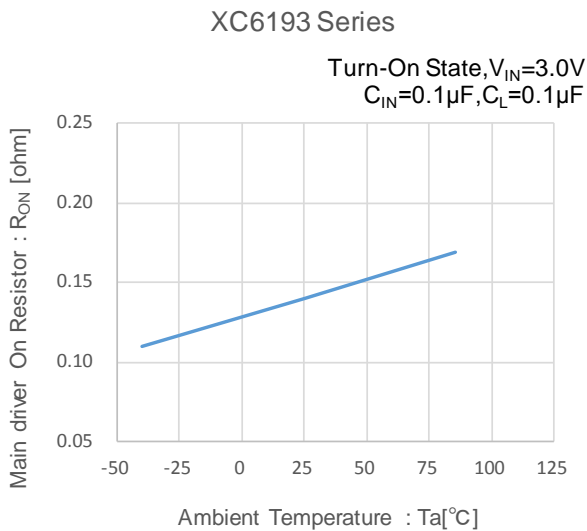
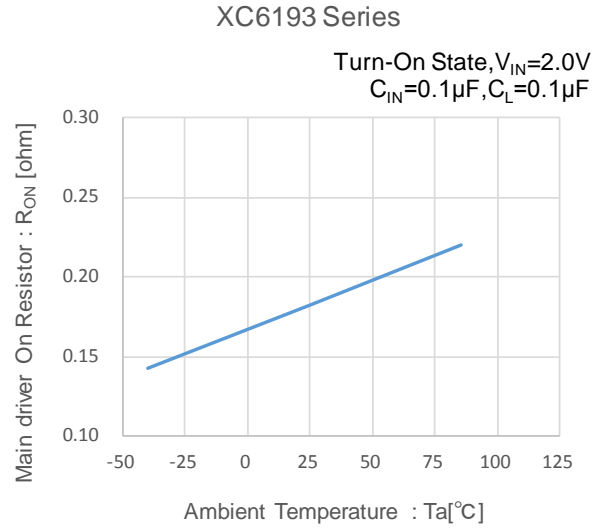
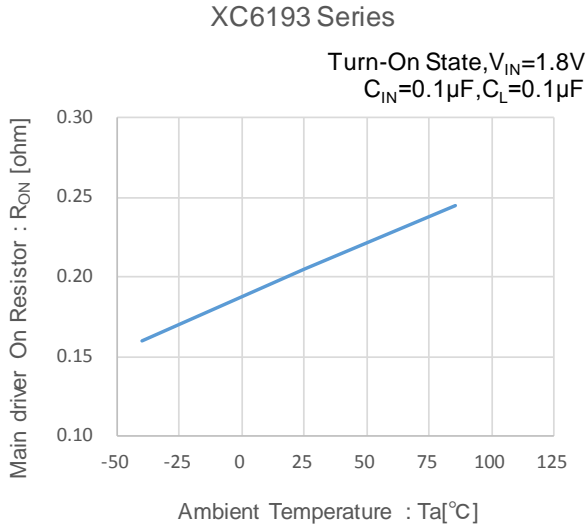
XC6193Ax15

$V_{IN}=3.0V, V_{SW}=V_{IN}>0V$
 $C_{IN}=0.1\mu F, C_L=0.1\mu F$



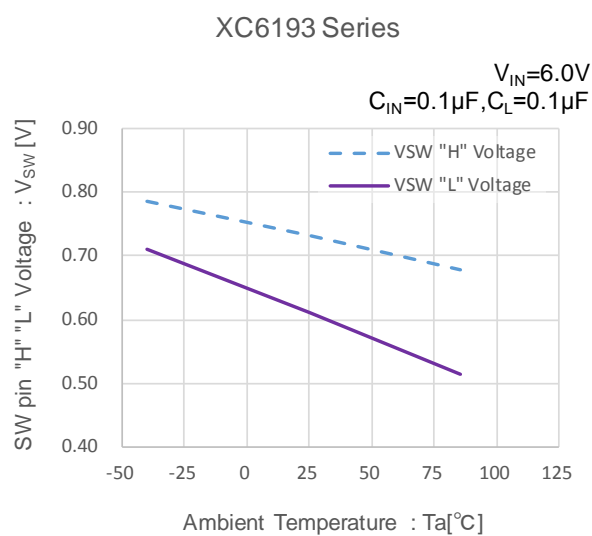
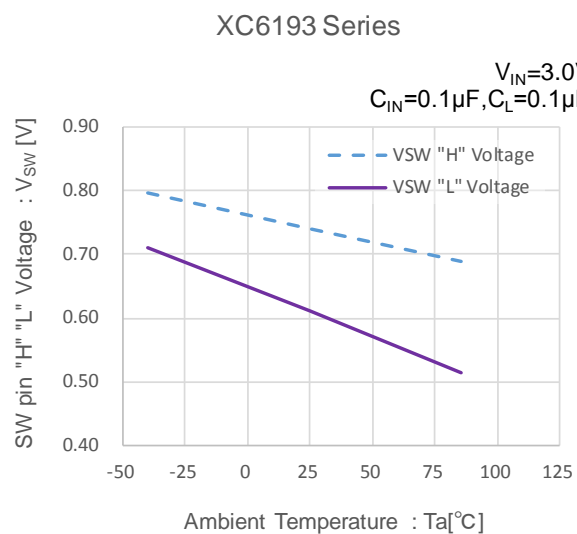
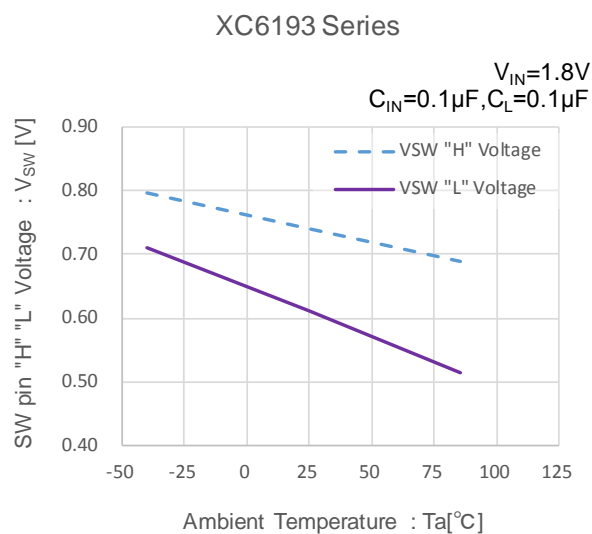
TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(9) Main driver On Resistor vs. Ambient Temperature



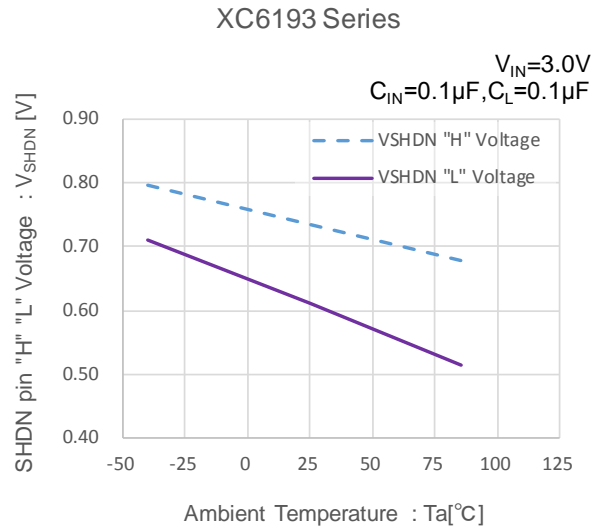
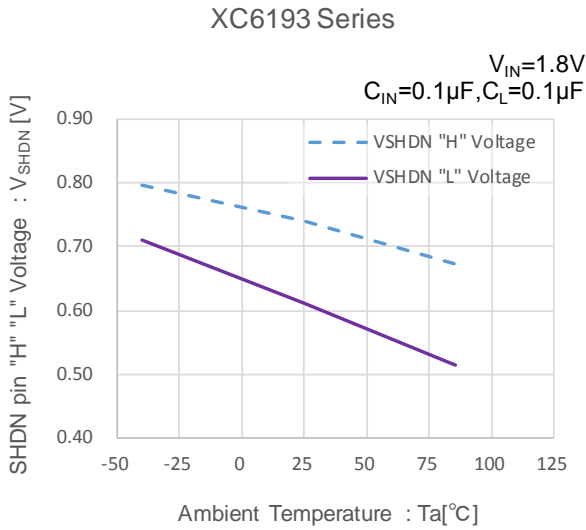
■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(10) SW pin "H" "L" Voltage vs. Ambient Temperature

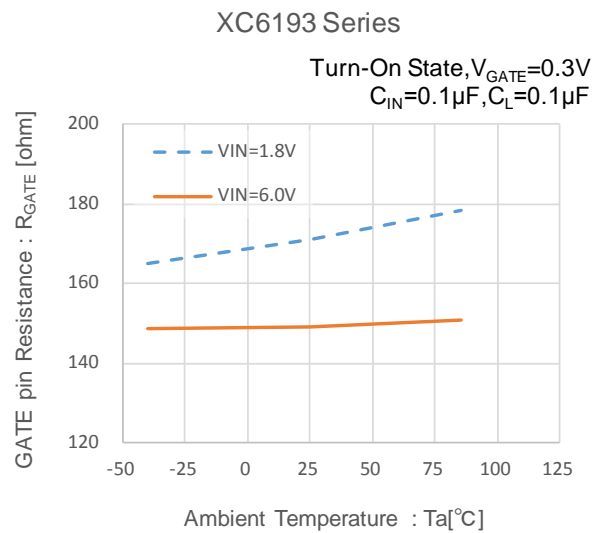
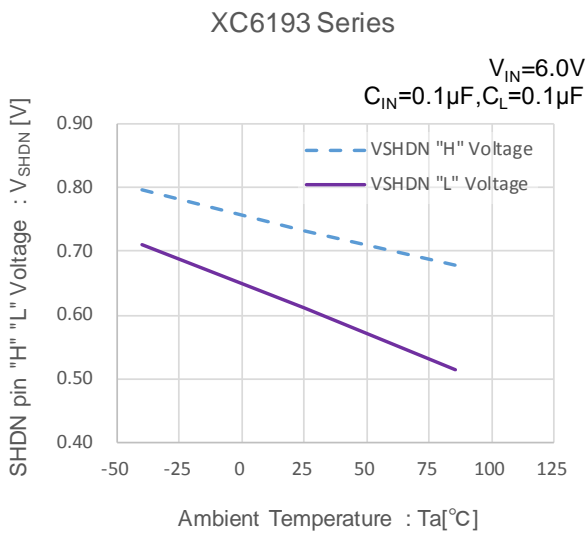


TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

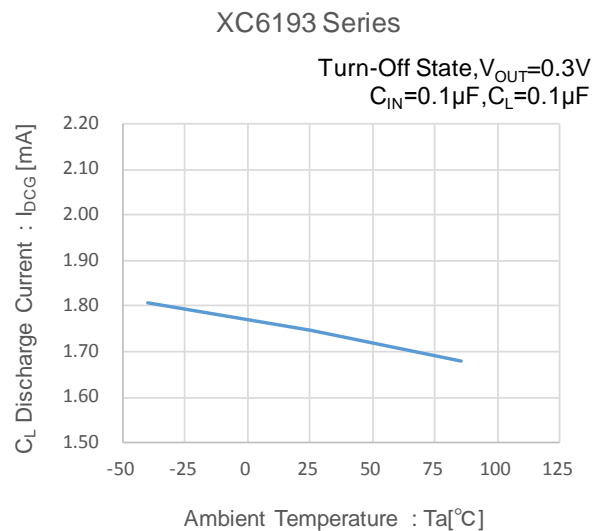
(11) SHDN pin "H" "L" Voltage vs. Ambient Temperature



(12) GATE pin Resistance vs. Ambient Temperature

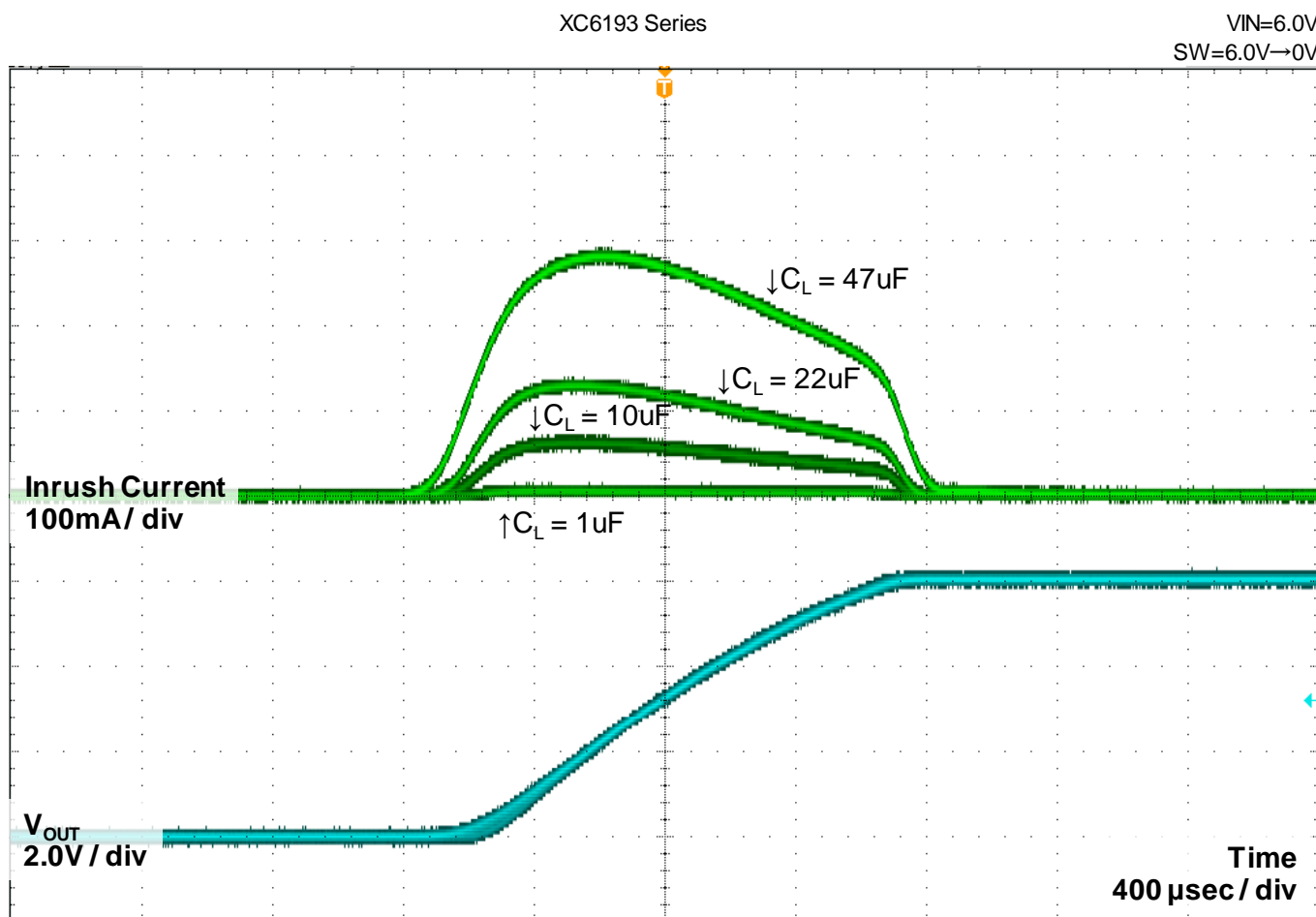


(13) C_L Discharge Current vs. Ambient Temperature



TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(14) Inrush Current caused by load capacitance



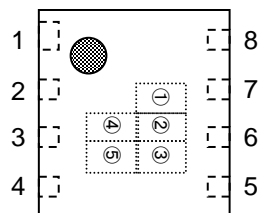
■ PACKAGING INFORMATION

For the latest package information go to, www.torexsemi.com/technical-support/packages

PACKAGE	OUTLIN / LAND PATTERN	THERMAL CHARACTERISTICS
USP-8B06	USP-8B06	USP-8B06 Power Dissipation

MARKING RULE

● USP-8B06



① represents product series.

MARK	PRODUCT SERIE
3	XC6193*****-G

② represents Type and Turn-On delay time

MARK	Type	Turn-On delay time	PRODUCT SERIE
0	Turn-on: By the SW pin Shut-down: By the SW pin or the SHDN pin	0.2s.	XC6193AA****-G
1		1s.	XC6193A1****-G
2		3s.	XC6193A3****-G
3		5s.	XC6193A5****-G
4	Turn-on: By the SW pin Shut-down: By the SHDN pin	0.2s.	XC6193BA****-G
5		1s.	XC6193B1****-G
6		3s.	XC6193B3****-G
7		5s.	XC6193B5****-G

③ represents Turn-Off delay time.

MARK	Turn-Off delay time	PRODUCT SERIE
A	3s.	XC6193**03**-G
B	5s.	XC6193**05**-G
C	10s.	XC6193**10**-G
D	15s.	XC6193**15**-G
0	-	XC6193B*NN**-G

④,⑤ represents production lot number

01~09, 0A~0Z, 11~9Z, A1~A9, AA~AZ, B1~ZZ in order.

(G, I, J, O, Q, W excluded)

* No character inversion used.

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